

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	ADG/18/11030	
1.3 Title of PCN	MDmesh M2 Technology 8" Wafer Front-end Capacity Extension - Ang Mo Kio (Singapore)	
1.4 Product Category	MDmesh M2 Technology	
1.5 Issue date	2018-08-03	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	MARSHALL DAVE
2.1.2 Phone	
2.1.3 Email	dave.marshall@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Maurizio GIUDICE
2.1.2 Marketing Manager	Paolo PETRALI
2.1.3 Quality Manager	Vincenzo MILITANO

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General	Wafer diameter modification	AMK Singapore

4. Description of change

	Old	New
4.1 Description	MDmesh M2 Technology manufactured in the 6" wafer line of Ang Mo Kio (Singapore)	MDmesh M2 Technology will be manufactured in the 8" wafer line of Ang Mo Kio (Singapore)
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no impact	

5. Reason / motivation for change

5.1 Motivation	Capacity Extension
5.2 Customer Benefit	MANUFACTURING FLEXIBILITY

6. Marking of parts / traceability of change

6.1 Description	by FG code and Q.A. number
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7. Timing / schedule

7.1 Date of qualification results	2018-07-26
7.2 Intended start of delivery	2018-11-04
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	11030 Rel15_18.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2018-08-03

9. Attachments (additional documentations)

11030 Public product.pdf
 11030 MDmesh M2 8" Wafer Front-end Capacity Extension - Ang Mo Kio (Singapore)....pdf
 11030 Rel15_18.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STFU16N65M2	
	STFU9N65M2	

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